Tetsu Tanaka

List of Publications by Year
in descending order

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300	4,365	23	54
papers	citations	h-index	g-index
		279701	161767

302	302	302	2766
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Scaling theory for double-gate SOI MOSFET's. IEEE Transactions on Electron Devices, 1993, 40, 2326-2329.	1.6	540
2	Efficacy of catheter-based renal denervation in the absence of antihypertensive medications (SPYRAL) Tj ETQq0 0 0 rgBT /Overlock 10 Tf 1444-1451.	6.3	351
3	High-Density Through Silicon Vias for 3-D LSIs. Proceedings of the IEEE, 2009, 97, 49-59.	16.4	267
4	Three-Dimensional Integration Technology Based on Wafer Bonding With Vertical Buried Interconnections. IEEE Transactions on Electron Devices, 2006, 53, 2799-2808.	1.6	210
5	A comparative study of advanced MOSFET concepts. IEEE Transactions on Electron Devices, 1996, 43, 1742-1753.	1.6	190
6	A capacitorless 1T-DRAM technology using gate-induced drain-leakage (GIDL) current for low-power and high-speed embedded memory. IEEE Transactions on Electron Devices, 2006, 53, 692-697.	1.6	131
7	Three-Dimensional Hybrid Integration Technology of CMOS, MEMS, and Photonics Circuits for Optoelectronic Heterogeneous Integrated Systems. IEEE Transactions on Electron Devices, 2011, 58, 748-757.	1.6	86
8	New Three-Dimensional Integration Technology Based on Reconfigured Wafer-on-Wafer Bonding Technique. , 2007, , .		77
9	Intramolecular hydrosilation of acetylenes: Regioselective functionalization of homopropargyl alcohols. Tetrahedron Letters, 1988, 29, 6955-6956.	0.7	75
10	Surface tension-driven chip self-assembly with load-free hydrogen fluoride-assisted direct bonding at room temperature for three-dimensional integrated circuits. Applied Physics Letters, 2010, 96, .	1.5	75
11	Ultrafast operation of V/sub th/-adjusted p/sup +/-n/sup +/ double-gate SOI MOSFET's. IEEE Electron Device Letters, 1994, 15, 386-388.	2.2	73
12	Wafer thinning, bonding, and interconnects induced local strain/stress in 3D-LSIs with fine-pitch high-density microbumps and through-Si vias. , 2010, , .		73
13	Silafunctional compounds in organic synthesis. 30. Intramolecular hydrosilation of alkenyl alcohols: A new approach to the regioselective synthesis of 1,2- and 1,3-diols. Tetrahedron Letters, 1986, 27, 3377-3380.	0.7	70
14	Tungsten Through-Silicon Via Technology for Three-Dimensional LSIs. Japanese Journal of Applied Physics, 2008, 47, 2801.	0.8	69
15	Identifying novel phenotypes of acute heart failure using cluster analysis of clinical variables. International Journal of Cardiology, 2018, 262, 57-63.	0.8	55
16	Analytical surface potential expression for thin-film double-gate SOI MOSFETs. Solid-State Electronics, 1994, 37, 327-332.	0.8	53
17	Evaluation of Cu Diffusion From Cu Through-Silicon Via (TSV) in Three-Dimensional LSI by Transient Capacitance Measurement. IEEE Electron Device Letters, 2011, 32, 940-942.	2.2	47
18	Three-dimensional integration technology based on reconfigured wafer-to-wafer and multichip-to-wafer stacking using self-assembly method. , 2009, , .		45

#	Article	IF	Citations
19	Multichip-to-Wafer Three-Dimensional Integration Technology Using Chip Self-Assembly With Excimer Lamp Irradiation. IEEE Transactions on Electron Devices, 2012, 59, 2956-2963.	1.6	44
20	Reconfigured-Wafer-to-Wafer 3-D Integration Using Parallel Self-Assembly of Chips With Cuâ€"SnAg Microbumps and a Nonconductive Film. IEEE Transactions on Electron Devices, 2014, 61, 533-539.	1.6	41
21	Impact of remnant stress/strain and metal contamination in 3D-LSIs with through-Si vias fabricated by wafer thinning and bonding. , 2009, , .		38
22	New heterogeneous multi-chip module integration technology using self-assembly method. , 2008, , .		37
23	Evaluation of Cu Contamination at Backside Surface of Thinned Wafer in 3-D Integration by Transient-Capacitance Measurement. IEEE Electron Device Letters, 2011, 32, 66-68.	2.2	35
24	10 µm fine pitch Cu/Sn micro-bumps for 3-D super-chip stack. , 2009, , .		32
25	Evaluation of objective nutritional indexes as predictors of one-year outcomes after transcatheter aortic valve implantation. Journal of Cardiology, 2019, 74, 34-39.	0.8	32
26	3D heterogeneous opto-electronic integration technology for system-on-silicon (SOS). , 2009, , .		31
27	High density 3D LSI technology using W/Cu hybrid TSVs. , 2011, , .		31
28	Multichip Self-Assembly Technology for Advanced Die-to-Wafer 3-D Integration to Precisely Align Known Good Dies in Batch Processing. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2011, 1, 1873-1884.	1.4	31
29	Leaflet Configuration and Residual Tricuspid Regurgitation After Transcatheter Edge-to-Edge TricuspidÂRepair. JACC: Cardiovascular Interventions, 2021, 14, 2260-2270.	1.1	30
30	Three-dimensional integration technology and integrated systems. , 2009, , .		27
31	Die-Level 3-D Integration Technology for Rapid Prototyping of High-Performance Multifunctionality Hetero-Integrated Systems. IEEE Transactions on Electron Devices, 2013, 60, 3842-3848.	1.6	26
32	Characteristics of microwave oscillations induced by spin transfer torque in a ferromagnetic nanocontact magnetoresistive element. Journal of Applied Physics, 2009, 105, 07D124.	1.1	25
33	Degradation of Memory Retention Characteristics in DRAM Chip by Si Thinning for 3-D Integration. IEEE Electron Device Letters, 2013, 34, 1038-1040.	2.2	25
34	A Cavity Chip Interconnection Technology for Thick MEMS Chip Integration in MEMS-LSI Multichip Module. Journal of Microelectromechanical Systems, 2010, 19, 1284-1291.	1.7	24
35	Self-Assembly of Chip-Size Components with Cavity Structures: High-Precision Alignment and Direct Bonding without Thermal Compression for Hetero Integration. Micromachines, 2011, 2, 49-68.	1.4	23
36	Impact of abdominal fat distribution, visceral fat, and subcutaneous fat on coronary plaque scores assessed by 320-row computed tomography coronary angiography. Atherosclerosis, 2019, 287, 155-161.	0.4	23

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37	A study of highly scalable DG-FinDRAM. IEEE Electron Device Letters, 2005, 26, 655-657.	2.2	22
38	Cu Retardation Performance of Extrinsic Gettering Layers in Thinned Wafers Evaluated by Transient Capacitance Measurement. Journal of the Electrochemical Society, 2011, 158, H795.	1.3	22
39	Through-Silicon Photonic Via and Unidirectional Coupler for High-Speed Data Transmission in Optoelectronic Three-Dimensional LSI. IEEE Electron Device Letters, 2012, 33, 221-223.	2.2	22
40	Self-Assembly Process for Chip-to-Wafer Three-Dimensional Integration. , 2007, , .		21
41	Memory characteristics of metal-oxide-semiconductor capacitor with high density cobalt nanodots floating gate and HfO2 blocking dielectric. Applied Physics Letters, 2009, 95, 033118.	1.5	21
42	Self-assembly technology for reconfigured wafer-to-wafer 3D integration. , 2010, , .		21
43	Barrier Properties of CVD Mn Oxide Layer to Cu Diffusion for 3-D TSV. IEEE Electron Device Letters, 2014, 35, 114-116.	2.2	19
44	Remarkable Suppression of Local Stress in 3D IC by Manganese Nitride-Based Filler with Large Negative CTE. , 2017, , .		19
45	New chip-to-wafer 3D integration technology using hybrid self-assembly and electrostatic temporary bonding. , 2012, , .		18
46	Analytical Models for Symmetric Thin-Film Double-Gate Silicon-on-Insulator Metal-Oxide-Semiconductor-Field-Effect-Transistors. Japanese Journal of Applied Physics, 1993, 32, 4916-4922.	0.8	17
47	Inhibition of IÎºB phosphorylation prevents load-induced cardiac dysfunction in mice. American Journal of Physiology - Heart and Circulatory Physiology, 2012, 303, H1435-H1445.	1.5	17
48	Oxide-Oxide Thermocompression Direct Bonding Technologies with Capillary Self-Assembly for Multichip-to-Wafer Heterogeneous 3D System Integration. Micromachines, 2016, 7, 184.	1.4	17
49	Novel Optical/Electrical Printed Circuit Board with Polynorbornene Optical Waveguide. Japanese Journal of Applied Physics, 2007, 46, 2395-2400.	0.8	16
50	Fully Implantable Retinal Prosthesis Chip with Photodetector and Stimulus Current Generator. , 2007, , .		16
51	Investigation of Local Bending Stress Effect on Complementary Metalâ€"Oxideâ€"Semiconductor Characteristics in Thinned Si Chip for Chip-to-Wafer Three-Dimensional Integration. Japanese Journal of Applied Physics, 2013, 52, 04CB11.	0.8	16
52	A parallel ADC for high-speed CMOS image processing system with 3D structure. , 2009, , .		15
53	Impacts of 3-D Integration Processes on Memory Retention Characteristics in Thinned DRAM Chip for High-Reliable 3-D DRAM. IEEE Transactions on Electron Devices, 2014, 61, 379-385.	1.6	15
54	New Magnetic Nanodot Memory with FePt Nanodots. Japanese Journal of Applied Physics, 2007, 46, 2167-2171.	0.8	14

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55	Multichip self-assembly technique on flexible polymeric substrate. , 2008, , .		14
56	Electrical Characterization of Metalâ€“Oxideâ€“Semiconductor Memory Devices with High-Density Self-Assembled Tungsten Nanodots. Japanese Journal of Applied Physics, 2008, 47, 2680-2683.	0.8	14
57	Impact of Cu Contamination on Memory Retention Characteristics in Thinned DRAM Chip for 3-D Integration. IEEE Electron Device Letters, 2012, 33, 1297-1299.	2.2	14
58	Impact of Cu diffusion from Cu through-silicon via (TSV) on device reliability in 3-D LSIs evaluated by transient capacitance measurement. , 2012, , .		14
59	Low-Resistance Cu-Sn Electroplatedâ€“Evaporated Microbumps for 3D Chip Stacking. Journal of Electronic Materials, 2012, 41, 720-729.	1.0	14
60	Reductant-Assisted Self-Assembly with Cu/Sn Microbump for Three-Dimensional Heterogeneous Integration. Japanese Journal of Applied Physics, 2013, 52, 04CB09.	0.8	14
61	Nucleation Kinetics of Electroless Cu Deposition on Ruthenium Using Glyoxylic Acid as a Reducing Agent. Journal of the Electrochemical Society, 2014, 161, D768-D774.	1.3	14
62	Impacts of Cu Contamination on Device Reliabilities in 3-D IC Integration. IEEE Transactions on Device and Materials Reliability, 2014, 14, 451-462.	1.5	14
63	Development of Eccentric Spin Coating of Polymer Liner for Low-Temperature TSV Technology With Ultra-Fine Diameter. IEEE Electron Device Letters, 2019, 40, 95-98.	2.2	14
64	Memory characteristics of self-assembled tungsten nanodots dispersed in silicon nitride. Applied Physics Letters, 2008, 93, 113115.	1.5	13
65	Direct multichip-to-wafer 3D integration technology using flip-chip self-assembly of NCF-covered known good dies. , 2014, , .		13
66	Source/drain contact resistance of silicided thin-film SOI MOSFET's. IEEE Transactions on Electron Devices, 1994, 41, 1007-1012.	1.6	12
67	Investigation of the effect of <i>in situ</i> annealing of FePt nanodots under high vacuum on the chemical states of Fe and Pt by x-ray photoelectron spectroscopy. Journal of Applied Physics, 2008, 104, .	1.1	12
68	Self-assembly technologies with high-precision chip alignment and fine-pitch microbump bonding for advanced die-to-wafer 3D integration. , 2011, , .		12
69	Non-conductive film and compression molding technology for self-assembly-based 3D integration. , 2012, , .		12
70	Hemodynamic correlates of nutritional indexes in heart failure. Journal of Cardiology, 2018, 71, 557-563.	0.8	12
71	Evaluation of Platinum-Black Stimulus Electrode Array for Electrical Stimulation of Retinal Cells in Retinal Prosthesis System. Japanese Journal of Applied Physics, 2007, 46, 2785-2791.	0.8	11
72	Pillar-shaped stimulus electrode array for high-efficiency stimulation of fully implantable epiretinal prosthesis. Journal of Micromechanics and Microengineering, 2012, 22, 105015.	1.5	11

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73	Impacts of static and dynamic local bending of thinned Si chip on MOSFET performance in 3-D stacked LSI. , 2013, , .		11
74	Flux-assisted self-assembly with microbump bonding for 3D heterogeneous integration. , 2013, , .		11
75	Self-Assembly and Electrostatic Carrier Technology for Via-Last TSV Formation Using Transfer Stacking-Based Chip-to-Wafer 3-D Integration. IEEE Transactions on Electron Devices, 2017, 64, 5065-5072.	1.6	11
76	Prognostic Impact of Computed Tomography-Derived Abdominal Fat Area on Transcatheter Aortic Valve Implantation. Circulation Journal, 2018, 82, 3082-3089.	0.7	11
77	The role of transcatheter aortic valve replacement in the patients with severe aortic stenosis requiring major non-cardiac surgery. Cardiovascular Intervention and Therapeutics, 2019, 34, 345-351.	1.2	11
78	A novel SPRAM (SPin-transfer torque RAM)-based reconfigurable logic block for 3D-stacked reconfigurable spin processor. , 2008, , .		10
79	Power Supply System Using Electromagnetic Induction for Three-Dimensionally Stacked Retinal Prosthesis Chip. Japanese Journal of Applied Physics, 2008, 47, 3244-3247.	0.8	10
80	Through Silicon photonic via (TSPV) with Si core for low loss and high-speed data transmission in opto-electronic 3-D LSI. , 2010, , .		10
81	Thermomechanical reliability challenges induced by high density Cu TSVs and metal micro-joining for 3-D ICs. , 2012, , .		10
82	Development of highly-reliable microbump bonding technology using self-assembly of NCF-covered KGDs and multi-layer 3D stacking challenges. , 2015, , .		10
83	Capillary Self-Assembly for 3D Heterogeneous System Integration and Packaging. MRS Advances, 2016, 1, 2355-2366.	0.5	10
84	Suppression of SiN-induced boron penetration by using SiH-free silicon nitride films formed by tetrachlorosilane and ammonia. IEEE Transactions on Electron Devices, 2002, 49, 1526-1531.	1.6	9
85	Cell characteristics of a multiple alloy nano-dots memory structure. Semiconductor Science and Technology, 2009, 24, 085013.	1.0	9
86	Formation of high density tungsten nanodots embedded in silicon nitride for nonvolatile memory application. Applied Physics Letters, 2009, 94, 063108.	1.5	9
87	Comparison of electrode materials for the use of retinal prosthesis. Bio-Medical Materials and Engineering, 2011, 21, 83-97.	0.4	9
88	Electrical evaluation of Cu contamination behavior at the backside surface of a thinned wafer by transient capacitance measurement. Semiconductor Science and Technology, 2011, 26, 025007.	1.0	9
89	Characterization of chip-level hetero-integration technology for high-speed, highly parallel 3D-stacked image processing system. , 2012, , .		9
90	Multiple optical stimulation to neuron using Si opto-neural probe with multiple optical waveguides and metal-cover for optogenetics. , 2013, 2013, 253-6.		9

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91	Impact of Chip-Edge Structures on Alignment Accuracies of Self-Assembled Dies for Microelectronic System Integration. Journal of Microelectromechanical Systems, 2016, 25, 91-100.	1.7	9
92	Immunoglobulin G4-Related CoronaryÂPeriarteritis With MultipleÂIntracoronary Images. JACC: Cardiovascular Interventions, 2019, 12, e59-e61.	1.1	9
93	Cu lateral interconnects formed between 100-µm-thick self-assembled chips on flexible substrates. , 2009, , .		8
94	Development of Si Neural Probe with Microfluidic Channel Fabricated Using Wafer Direct Bonding. Japanese Journal of Applied Physics, 2009, 48, 04C189.	0.8	8
95	High-step-coverage Cu-lateral interconnections over 100 Âµm thick chips on a polymer substrateâ€"an alternative method to wire bonding. Journal of Micromechanics and Microengineering, 2012, 22, 085033.	1.5	8
96	Deteriorated Device Characteristics in 3D-LSI Caused by Distorted Silicon Lattice. IEEE Transactions on Electron Devices, 2014, 61, 540-547.	1.6	8
97	Temporary spin-on glass bonding technologies for via-last/backside-via 3D integration using multichip self-assembly. , 2014, , .		8
98	Vertical-cavity surface-emitting laser chip bonding by surface-tension-driven self-assembly for optoelectronic heterogeneous integration. Japanese Journal of Applied Physics, 2015, 54, 030206.	0.8	8
99	Applications of three-dimensional LSI. MRS Bulletin, 2015, 40, 242-247.	1.7	8
100	Effect of local stress induced by thermal expansion of underfill in three-dimensional stacked IC. Japanese Journal of Applied Physics, 2016, 55, 04EC03.	0.8	8
101	Electrical conductance properties for magnetic tunnel junctions with MgO barriers. Journal of Magnetism and Magnetic Materials, 2008, 320, 2959-2962.	1.0	7
102	Development of Si Double-Sided Microelectrode for Platform of Brain Signal Processing System. Japanese Journal of Applied Physics, 2009, 48, 04C194.	0.8	7
103	Fundamental Study of Complementary Metal Oxide Semiconductor Image Sensor for Three-Dimensional Image Processing System. Japanese Journal of Applied Physics, 2009, 48, 04C077.	0.8	7
104	Mechanical characteristics of thin dies/wafers in three-dimensional large-scale integrated systems. , 2013, , .		7
105	Impacts of Cu contamination in 3D integration process on memory retention characteristics in thinned DRAM chip. , 2014, , .		7
106	Replacing the PECVD-SiO<inf>2</inf> in the through-silicon via of high-density 3D LSIs with highly scalable low cost organic liner: Merits and demerits. , 2014, , .		7
107	Novel reconfigured wafer-to-wafer (W2W) hybrid bonding technology using ultra-high density nano-Cu filaments for exascale 2.5D/3D integration. , 2015, , .		7
108	Role of Bath Composition in Electroless Cu Seeding on Co Liner for through-Si Vias. ECS Journal of Solid State Science and Technology, 2015, 4, N3108-N3112.	0.9	7

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109	Prognostic impact of electrocardiographic left ventricular hypertrophy following transcatheter aortic valve replacement. Journal of Cardiology, 2021, 77, 346-352.	0.8	7
110	Prognostic impact of arterial stiffness following transcatheter aortic valve replacement. Journal of Cardiology, 2021, 78, 37-43.	0.8	7
111	Prognostic impact of hepatorenal function in patients undergoing transcatheter tricuspid valve repair. Scientific Reports, 2021, 11, 14420.	1.6	7
112	Leakage Current Characteristics of the Multiple Metal Alloy Nanodot Memory. Journal of the Korean Physical Society, 2010, 57, 1248-1252.	0.3	7
113	Development of Retinal Prosthesis Module for Fully Implantable Retinal Prosthesis. IFMBE Proceedings, 2010, , 1625-1628.	0.2	7
114	A resilient 3-D stacked multicore processor fabricated using die-level 3-D integration and backside TSV technologies. , 2014, , .		6
115	Experimental evaluation of stimulus current generator with Laplacian edge-enhancement for 3-D stacked retinal prosthesis chip. , 2017, , .		6
116	Development of integrated photoplethysmographic recording circuit for trans-nail pulse-wave monitoring system. Japanese Journal of Applied Physics, 2018, 57, 04FM11.	0.8	6
117	Tunnel field-effect transistor charge-trapping memory with steep subthreshold slope and large memory window. Japanese Journal of Applied Physics, 2018, 57, 04FE07.	0.8	6
118	Development of Biosignal Recording Board System with Agile Control of Circuit Characteristics for Various Biosignals. Electronics and Communications in Japan, 2018, 101, 47-54.	0.3	6
119	Charge-Trap-Free Polymer-Liner Through-Silicon Vias for Reliability Improvement of 3D ICs. , 2018, , .		6
120	Self-Assembly Technologies for FlexTrateâ„¢. , 2018, , .		6
121	Transcatheter aortic valve implantation in a patient with severe aortic valve stenosis, colon cancer, and obstructive ileus: A case report. Journal of Cardiology Cases, 2018, 17, 163-166.	0.2	6
122	Mechanical and Electrical Characterization of FOWLP-Based Flexible Hybrid Electronics (FHE) for Biomedical Sensor Application. , 2019, , .		6
123	Investigation of TSV Liner Interface With Multiwell Structured TSV to Suppress Noise Propagation in Mixed-Signal 3D-IC. IEEE Journal of the Electron Devices Society, 2019, 7, 1225-1231.	1.2	6
124	FOWLP-Based Flexible Hybrid Electronics with 3D-IC Chiplets for Smart Skin Display. , 2021, , .		6
125	Study of Al-doped ZnO Transparent Stimulus Electrode for Fully Implantable Retinal Prosthesis with Three-dimensionally Stacked Retinal Prosthesis Chip. Sensors and Materials, 2018, , 225.	0.3	6
126	11B NMR study of superconductivity in YRuB2 and LuRuB2. Journal of Magnetism and Magnetic Materials, 2007, 310, 581-583.	1.0	5

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127	Low-Loss Optical Interposer with Recessed Vertical-Cavity Surface-Emitting Laser Diode and Photodiode Chips into Si Substrate. Japanese Journal of Applied Physics, 2008, 47, 2936-2940.	0.8	5
128	Development of double-sided Si neural probe with microfluidic channels using wafer direct bonding technique. , 2009, , .		5
129	Trimer V³⁺ Spin Singlet State and Pseudo Gap in LiVS₂ Studied by ⁵¹V and ⁷Li Nuclear Magnetic Resonance. Journal of the Physical Society of Japan, 2009, 78, 054709.	0.7	5
130	Cannula-aided penetration: A simple method to insert structurally weak electrodes into brain through the dura mater. Neuroscience Research, 2009, 65, 126-129.	1.0	5
131	Impact of microbump induced stress in thinned 3D-LSIs after wafer bonding. , 2010, , .		5
132	Development of Si neural probe with optical waveguide for highly accurate optical stimulation of neuron. , 2011, , .		5
133	Chip-based hetero-integration technology for high-performance 3D stacked image sensor. , 2012, , .		5
134	3D Integration technologies using self-assembly and electrostatic temporary multichip bonding. , 2013, , .		5
135	Minimization of Keep-Out-Zone (KOZ) in 3D IC by local bending stress suppression with low temperature curing adhesive. , 2014, , .		5
136	Effects of electro-less Ni layer as barrier/seed layers for high reliable and low cost Cu TSV. , 2014, , .		5
137	Plasma assisted multichip-to-wafer direct bonding technology for self-assembly based 3D integration. , 2015, , .		5
138	Heterogeneous 3-D Integration Using Self-Assembly and Electrostatic Bonding. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 1000-1006.	1.4	5
139	3D-IC technology and reliability challenges. , 2017, , .		5
140	3-D Sidewall Interconnect Formation Climbing Over Self-Assembled KGDs for Large-Area Heterogeneous Integration. IEEE Transactions on Electron Devices, 2017, 64, 2912-2918.	1.6	5
141	PPG and SpO₂ Recording Circuit with Ambient Light Cancellation for Trans-Nail Pulse-Wave Monitoring System. , 2019, , .		5
142	High-Thermoresistant Temporary Bonding Technology for Multichip-to-Wafer 3-D Integration With Via-Last TSVs. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 181-188.	1.4	5
143	RDL-first Flexible FOWLP Technology with Dielets Embedded in Hydrogel. , 2020, , .		5
144	Significant Die-Shift Reduction and <i>Î¼</i>LED Integration Based on Die-First Fan-Out Wafer-Level Packaging for Flexible Hybrid Electronics. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 1419-1422.	1.4	5

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145	<scp>Onâ€wafer</scp> thermomechanical characterization of a thin film polyimide formed by vapor deposition polymerization for <scp>throughâ€silicon</scp> via applications: Comparison to <scp>plasmaâ€enhanced</scp> chemical vapor deposition <scp>SiO₂</scp>. Journal of Polymer Science, 2020, 58, 2248-2258.	2.0	5
146	Early response of right-ventricular function to percutaneous mitral valve repair. Clinical Research in Cardiology, 2022, 111, 859-868.	1.5	5
147	Room-Temperature Cu Direct Bonding Technology Enabling 3D Integration with Micro-LEDs. , 2022, , .		5
148	U-grooved SIT CMOS technology with 3 fJ and 49 ps (7 mW, 350 fJ) operation. IEEE Transactions on Electron Devices, 1990, 37, 1877-1883.	1.6	4
149	New Reconfigurable Memory Architecture for Parallel Image-Processing LSI with Three-Dimensional Structure. Japanese Journal of Applied Physics, 2008, 47, 2774-2778.	0.8	4
150	Heterogeneous integration technology for MEMS-LSI multi-chip module. , 2009, , .		4
151	Optical Interposer Technology using Buried Vertical-Cavity Surface-Emitting Laser Chip and Tapered Through-Silicon Via for High-Speed Chip-to-Chip Optical Interconnection. Japanese Journal of Applied Physics, 2009, 48, 04C113.	0.8	4
152	Three-dimensional integration technology using through-si via based on reconfigured wafer-to-wafer bonding. , 2010, , .		4
153	3D integration technology and reliability challenges. , 2011, , .		4
154	MOSFET Nonvolatile Memory with High-Density Cobalt-Nanodots Floating Gate and $hbox{HfO}_{f 2}$ High-k Blocking Dielectric. IEEE Nanotechnology Magazine, 2011, 10, 528-531.	1.1	4
155	Multilevel Charge Storage in a Multiple Alloy Nanodot Memory. Japanese Journal of Applied Physics, 2011, 50, 095001.	0.8	4
156	Novel detachable bonding process with wettability control of bonding surface for versatile chip-level 3D integration. , 2012, , .		4
157	W/Cu TSVs for 3D-LSI with minimum thermo-mechanical stress. , 2012, , .		4
158	Highly efficient TSV repair technology for resilient 3-D stacked multicore processor system. , 2013, , .		4
159	Fabrication and In vivo Evaluation of Poly(3,4-ethylenedioxythiophene) Stimulus Electrodes for Fully Implantable Retinal Prosthesis. Japanese Journal of Applied Physics, 2013, 52, 04CL03.	0.8	4
160	Reconfigured multichip-on-wafer (mCoW) Cu/oxide hybrid bonding technology for ultra-high density 3D integration using recessed oxide, thin glue adhesive, and thin metal capping layers. , 2015, , .		4
161	Design and evaluation of area-efficient and wide-range impedance analysis circuit for multichannel high-quality brain signal recording system. Japanese Journal of Applied Physics, 2016, 55, 04EM12.	0.8	4
162	Novel Hybrid Bonding Technology Using Ultra-High Density Cu Nano-Pillar for Exascale 2.5D/3D Integration. IEEE Electron Device Letters, 2016, 37, 81-83.	2.2	4

#	ARTICLE	IF	CITATIONS
163	Minimized hysteresis and low parasitic capacitance TSV with PBO (polybenzoxazole) liner to achieve ultra-high-speed data transmission. , 2017, , .		4
164	The Effect of Mechanical Stress on Cell Characteristics in MONOS Structures. IEEE Transactions on Electron Devices, 2018, 65, 4313-4319.	1.6	4
165	The role of the renal resistance index in patients with heart failure with reduced or preserved ejection fraction. Journal of Cardiology, 2021, 78, 301-307.	0.8	4
166	Integration of Damage-less Probe Cards Using Nano-TSV Technology for Microbumped Wafer Testing. , 2021, , .		4
167	Novel Retinal Prosthesis System with Three Dimensionally Stacked LSI Chip. Solid-State Device Research Conference, 2008 ESSDERC 2008 38th European, 2006, , .	0.0	3
168	High Performance Polynorbornene Optical Waveguide for Opto-Electric Interconnections. , 2007, , .		3
169	A closed-loop power control function for bio-implantable devices. , 2008, , .		3
170	MOSFET nonvolatile memory with a high-density tungsten nanodot floating gate formed by self-assembled nanodot deposition. Semiconductor Science and Technology, 2009, 24, 045022.	1.0	3
171	Characteristics of a Multiple Alloy Nanodot Memory with an Enhanced Charge Storage Capability. Japanese Journal of Applied Physics, 2010, 49, 074201.	0.8	3
172	NMR study of magnetic excitation in LiVX₂(X = O, S). Journal of Physics: Conference Series, 2011, 320, 012028.	0.3	3
173	Characterization and reliability of 3D LSI and SiP. , 2013, , .		3
174	A block-parallel ADC with digital noise cancelling for 3-D stacked CMOS image sensor. , 2013, , .		3
175	Impact of 3-D integration process on memory retention characteristics in thinned DRAM chip for 3-D memory. , 2013, , .		3
176	A new temporary bonding technology with spin-on glass and hydrogenated amorphous Si for 3D LSIs. , 2014, , .		3
177	Solid State Devices and Materials. Japanese Journal of Applied Physics, 2014, 53, 04E001.	0.8	3
178	New concept of TSV formation methodology using Directed Self-Assembly (DSA). , 2016, , .		3
179	Back-via 3D integration technologies by temporary bonding with thermoplastic adhesives and visible-laser debonding. , 2016, , .		3
180	Continuous Peripheral Blood Pressure Measurement with ECG and PPG Signals at Fingertips. , 2018, , .		3

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